



## P-Channel Enhancement Mode MOSFET

TDM2305

Absolute Maximum Ratings ( $T_A = 25^\circ\text{C}$  unless otherwise noted)

Symbol	Parameter		Rating	Unit
VDSS	Drain-Source Voltage		-20	V
VGSS	Gate-Source Voltage		$\pm 12$	
ID*	Continuous Drain Current		-3.5	A
IDM*	300 $\mu\text{s}$ Pulsed Drain Current	VGS=-4.5V	-14	
IS*	Diode Continuous Forward Current		-1.2	A
TJ	Maximum Junction Temperature		150	$^\circ\text{C}$
TSTG	Storage Temperature Range		-55 to 150	
PD*	Maximum Power Dissipation	TA=25 $^\circ\text{C}$	0.83	W
		TA=100 $^\circ\text{C}$	0.3	
R $\theta$ JA*	Thermal Resistance-Junction to Ambient		150	$^\circ\text{C}/\text{W}$

Note: \*

Surface Mounted on 1in<sup>2</sup> pad area,  $t \leq 10\text{sec}$ .Electrical Characteristics ( $T_A = 25^\circ\text{C}$  unless otherwise noted)

Symbol	Parameter	Test Condition	TDM2305			Unit
			Min.	Typ.	Max.	
<b>Static Characteristics</b>						
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>DS</sub> =-250 $\mu\text{A}$	-20			V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> =-16V, V <sub>GS</sub> =0V T <sub>J</sub> =85 $^\circ\text{C}$			-1 -30	$\mu\text{A}$
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>DS</sub> =-250 $\mu\text{A}$	-0.5	-0.7	-1	V
I <sub>GSS</sub>	Gate Leakage Current	V <sub>GS</sub> = $\pm 12\text{V}$ , V <sub>DS</sub> =0V			$\pm 100$	nA
R <sub>DS(ON)</sub> a	Drain-Source On-state Resistance	V <sub>GS</sub> =-4.5V, I <sub>DS</sub> =-3.5A		60	70	m $\Omega$
		V <sub>GS</sub> =-2.5V, I <sub>DS</sub> =-3A		70	85	
		V <sub>GS</sub> =-1.8V, I <sub>DS</sub> =-3A		83	105	
V <sub>SD</sub> a	Diode Forward Voltage	I <sub>SD</sub> =-1.25A, V <sub>GS</sub> =0V		-0.7	-1.3	V
<b>Gate Charge Characteristics</b> b						
Q <sub>g</sub>	Total Gate Charge	V <sub>DS</sub> =-10V, V <sub>GS</sub> =-4.5V, I <sub>DS</sub> =-3A		10.5	15	
Q <sub>gs</sub>	Gate-Source Charge			2.1		nC

Electrical Characteristics (Cont.) ( $T_A = 25^\circ\text{C}$  unless otherwise noted)

Symbol	Parameter	Test Condition	TDM2305			Unit
			Min.	Typ.	Max.	
<b>Dynamic Characteristics<sup>b</sup></b>						
$R_G$	Gate Resistance	$V_{GS}=0V, V_{DS}=0V, F=1\text{MHz}$		7.5		$\Omega$
$C_{iss}$	Input Capacitance	$V_{GS}=0V, V_{DS}=-15V,$ Frequency=1.0MHz		1050		PF
$C_{oss}$	Output Capacitance			190		
$C_{riss}$	Reverse Transfer Capacitance			150		
$t_{d(ON)}$	Turn-on Delay Time	$V_{DD}=-10V, R_L=10\Omega,$ $I_{DS}=-1A, V_{GEN}=-4.5V,$ $R_G=6\Omega$		5	10	Ns
$T_r$	Turn-on Rise Time			12	23	
$t_{d(OFF)}$	Turn-off Delay Time			66	120	
$T_f$	Turn-off Fall Time			39	71	

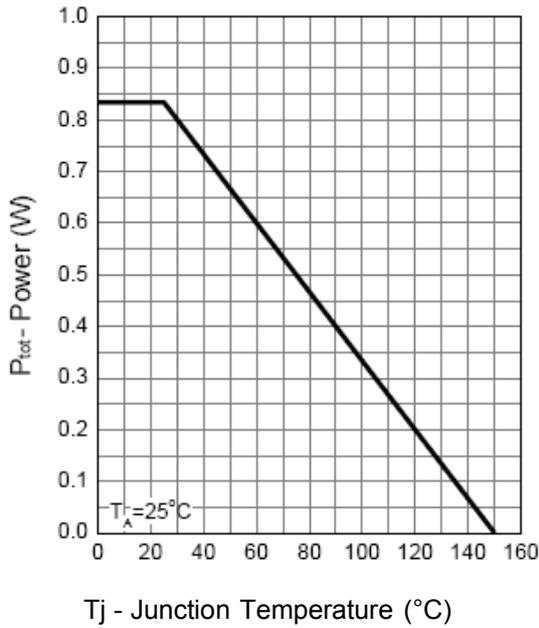
## Notes:

a : Pulse test ; pulse width  $\leq 300\mu\text{s}$ , duty cycle  $\leq 2\%$ .

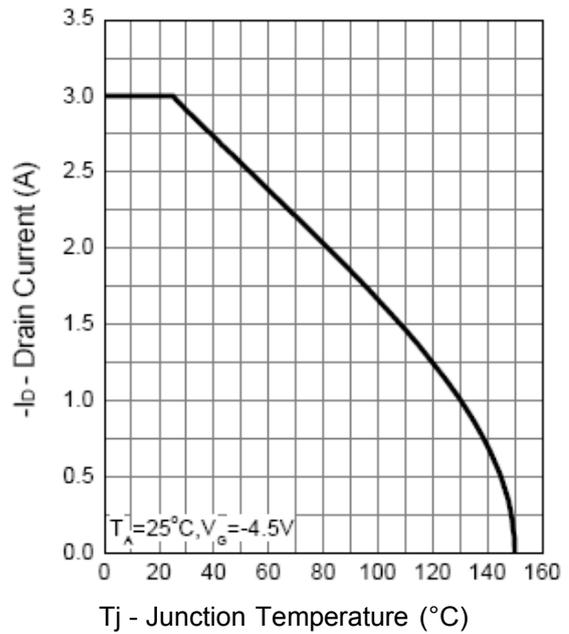
b : Guaranteed by design, not subject to production testing.

Typical Characteristics

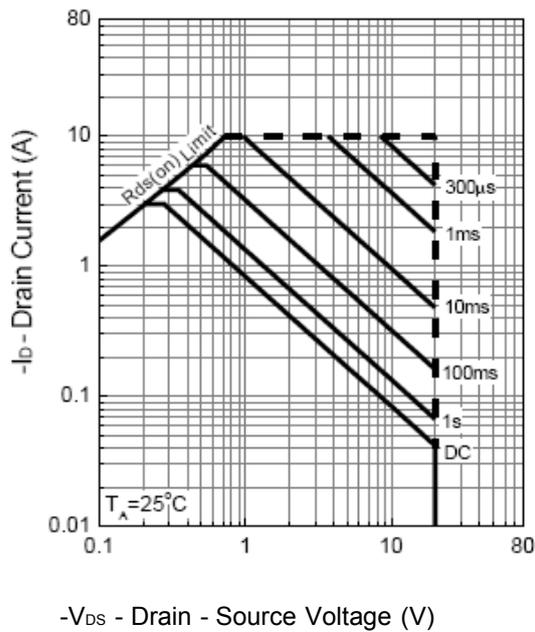
Power Dissipation



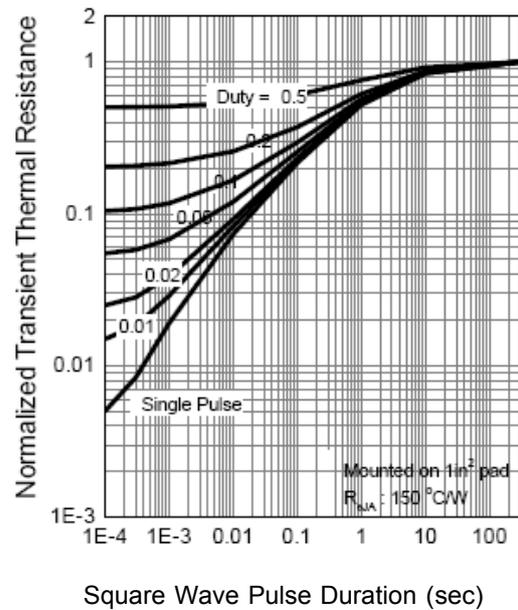
Drain Current



Safe Operation Area

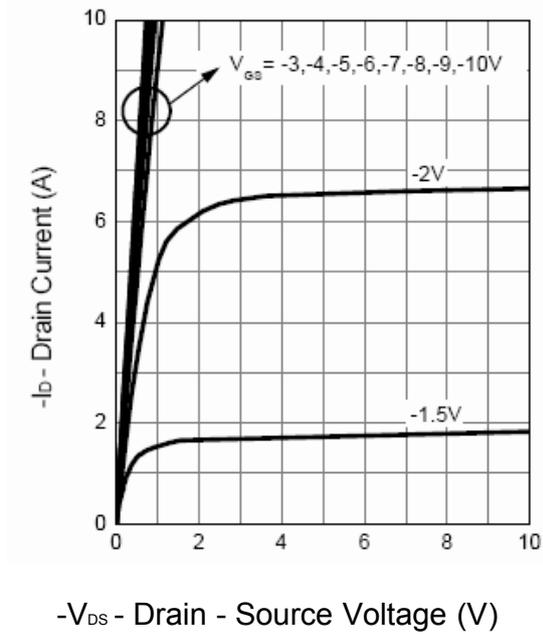


Thermal Transient Impedance

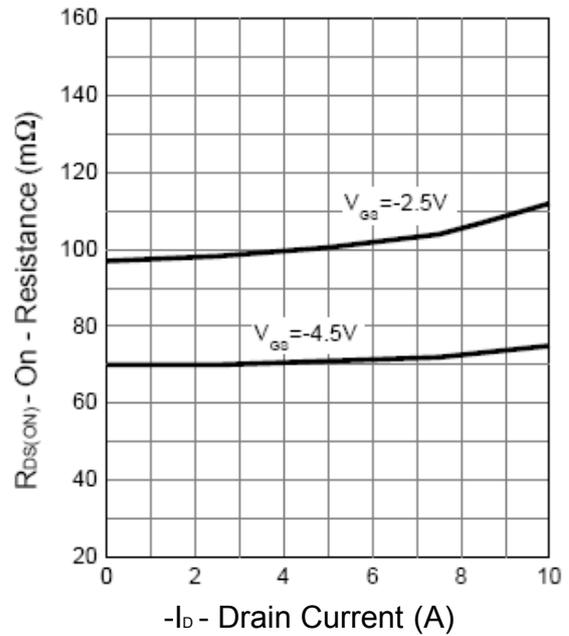


## Typical Characteristics (Cont.)

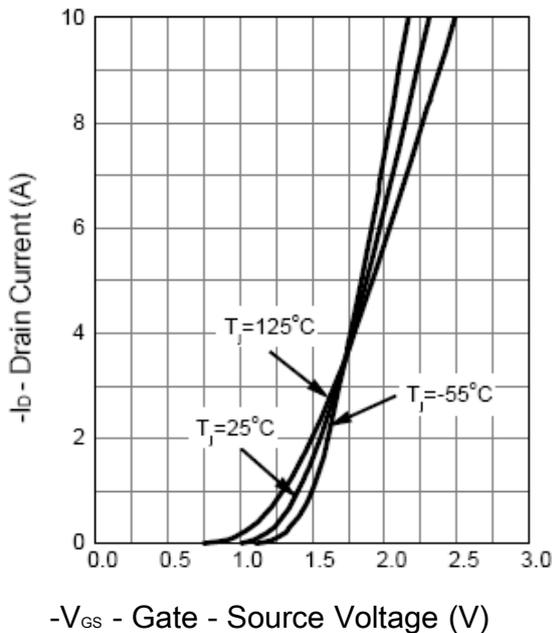
### Output Characteristics



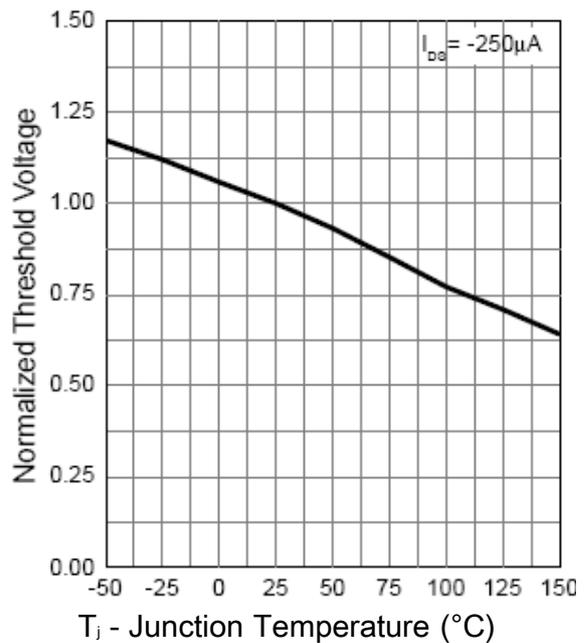
### Drain-Source On Resistance



### Transfer Characteristics

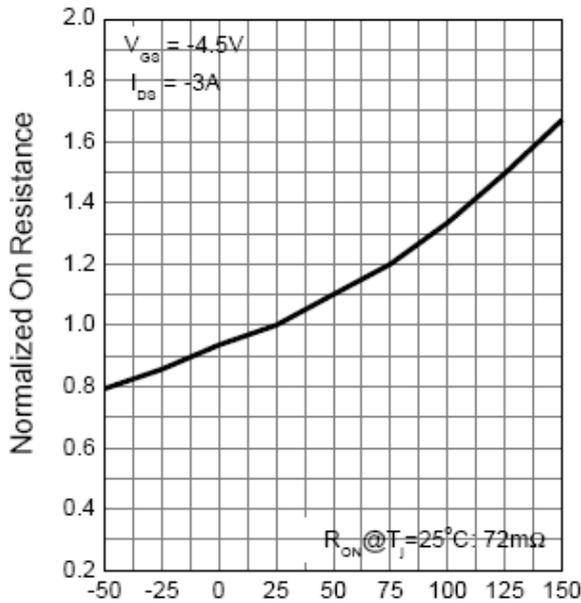


### Gate Threshold Voltage



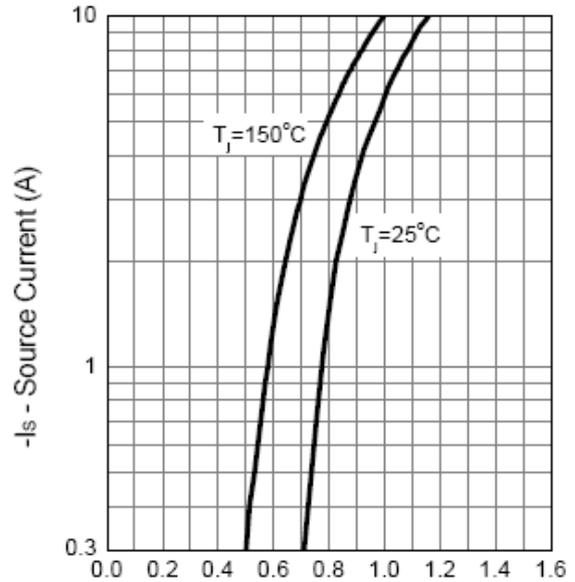
## Typical Characteristics (Cont.)

### Drain-Source On Resistance



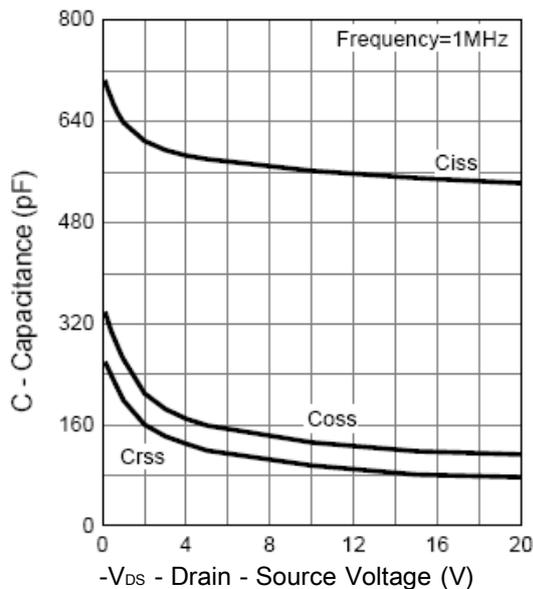
$T_j$  - Junction Temperature (°C)

### Source-Drain Diode Forward



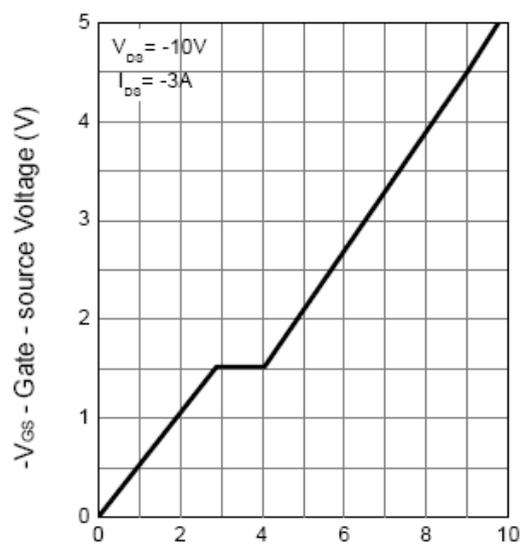
$-V_{SD}$  - Source - Drain Voltage (V)

### Capacitance



$-V_{DS}$  - Drain - Source Voltage (V)

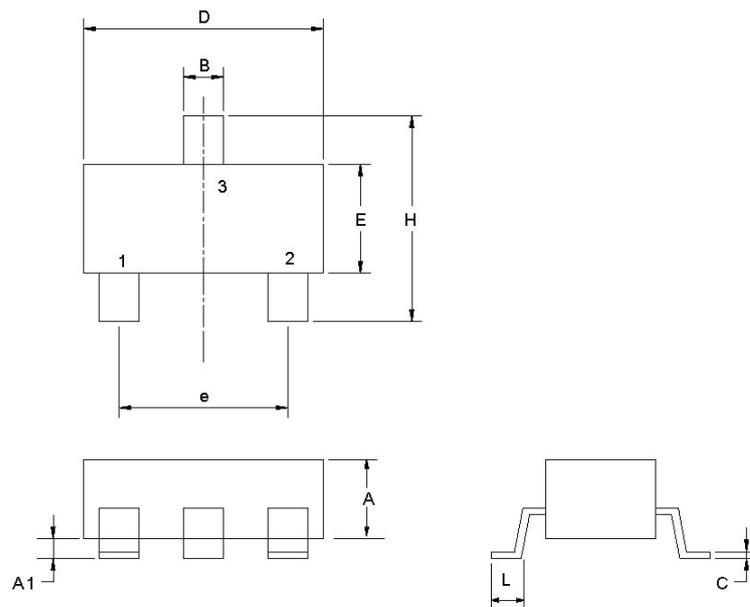
### Gate Charge



$Q_G$  - Gate Charge (nC)

### Packaging Information

SOT23-3L



Dim	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	1.00	1.30	0.039	0.051
A1	0.00	0.10	0.000	0.004
B	0.35	0.51	0.014	0.020
C	0.10	0.25	0.004	0.010
D	2.70	3.10	0.106	0.122
E	1.40	1.80	0.055	0.071
e	1.90/2.1 BSC.		0.075/0.083 BSC.	
H	2.40	3.00	0.094	0.118
L	0.37		0.015	